CLAIMS

1. A package substrate, comprising:

a body (10), wherein the body (10) comprises an opening region (11); and

a conductive layer (20), wherein the conductive layer (20) is disposed at the opening region (11), the conductive layer (20) comprises a first conductive bridge (21) and a second conductive bridge (22), and the first conductive bridge (21) and the second conductive bridge (22) are disposed at intervals,

wherein the first conductive bridge (21) is provided with at least one first via (211);

wherein the at least one first via (211) comprises a plurality of first vias, and the plurality of first vias are disposed at intervals within the first conductive bridge (21).

2. The package substrate of claim 1, wherein the plurality of first vias are disposed at intervals along a length direction of the first conductive bridge (21).

3. The package substrate of claim 1, wherein a gap (24) is formed between the first conductive bridge (21) and the second conductive bridge (22).

4. The package substrate of claim 3, wherein the gap (24) is filled with a heat-conductive portion.

5. The package substrate of claim 1, wherein a via wall of the at least one first via (211) comprises at least one of a cambered surface and a plane.

6. The package substrate of claim 1, wherein the second conductive bridge (22) is provided with at least one second via (221).

7. The package substrate of claim 6, wherein the at least one second via (221) comprises a plurality of second vias.

8. The package substrate of claim 1, wherein the conductive layer (20) further comprises:

a third conductive bridge (23), wherein the third conductive bridge (23) and the first conductive bridge (21) are disposed at intervals, and the third conductive bridge (23) and the second conductive bridge (22) are disposed at intervals.

9. The package substrate of claim 8, wherein the third conductive bridge (23) is provided with at least one third via (231).

10. The package substrate of claim 8, wherein the first conductive bridge (21), the second conductive bridge (22), and the third conductive bridge (23) are disposed at intervals along a length direction of the opening region (11).

11. The package substrate of claim 10, wherein a distance between the first conductive bridge (21) and the second conductive bridge (22) is equal to a distance between the second conductive bridge (22) and the third conductive bridge (23).

12. The package substrate of claim 9, wherein the at least one third via (231) comprises a plurality of third vias.

13. The package substrate of claim 1, wherein the first conductive bridge (21) has a rectangular structure.

14. The package substrate of claim 1, wherein the first conductive bridge (21) comprises:

a first bridge segment (212), wherein two ends of the first bridge segment (212) are connected to the body (10);

a second bridge segment (213), wherein two ends of the second bridge segment (213) are connected to the body (10), and the first bridge segment (212) and the second bridge segment (213) are disposed at intervals; and

a third bridge segment (214), wherein two ends of the third bridge segment (214) are connected to the first bridge segment (212) and the second bridge segment (213) respectively;

wherein at least one of the first bridge segment (212), the second bridge segment (213), and the third bridge segment (214) is provided with the at least one first via (211).

15. The package substrate of claim 1, wherein the first conductive bridge (21) comprises:

a first bridge segment (212), wherein one end of the first bridge segment (212) is connected to the body (10);

a second bridge segment (213), wherein one end of the second bridge segment (213) is connected to the body (10); and

a third bridge segment (214), wherein one end of the third bridge segment (214) is connected to other end of the first bridge segment (212), the one end of the third bridge

segment (214) is connected to other end of the second bridge segment (213), and other end of the third bridge segment (214) is connected to the body (10);

wherein at least one of the first bridge segment (212), the second bridge segment (213), and the third bridge segment (214) is provided with the at least one first via (211).

16. The package substrate of claim 14 or 15, wherein the first bridge segment (212), the second bridge segment (213), and the third bridge segment (214) are of an integrally formed structure.

17. The package substrate of claim 1, wherein the package substrate further comprises:

conductive bumps (30), wherein the conductive bumps (30) are disposed on the body (10) and located outside the opening region (11);

wherein the conductive bumps (30) are disposed above and below the opening region (11), and wall surfaces of the opening region (11) are located between the conductive bumps (30).

18. The package substrate of claim 17, wherein the wall surfaces comprise two opposing first wall surfaces (111) and two opposing second wall surfaces (112), the first wall surfaces (111) extend along a width direction of the opening region (11), and the second wall surfaces (112) extend along a length direction of the opening region (11);

wherein connection lines of outer edges of upper and lower two of the conductive bumps (30) on outermost sides enclose a limiting region (31), and the first wall surface (111) is located within the limiting region (31).

19. A semiconductor structure, comprising a chip and a package substrate of any one of claims 1 to 18.